

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (CURRENTLY AMENDED) A solid-state imaging device, comprising:
  - a substrate ~~with a flat board form that is made of an insulating resin;~~
  - an imaging element that is ~~fixed onto~~ mounted on the substrate;
  - a rib with ~~a rectangular frame form in a planar shape, which is provided on the~~ substrate so as to surround the imaging element;
  - a transparent plate that is fixed to a top face of the rib;
  - a plurality of wiring[[s]] ~~for conducting electricity from~~ connecting electrically inside of a package [[to]] with outside of the package, the package being comprised of the substrate, the rib and the transparent plate; and
  - a thin metal wire[[s]] ~~provided in a space within the package, which connect for~~ connecting an electrode electrodes of the imaging element with the respective wiring[[s]].

wherein ~~each of the plurality of wirings~~ includes: an internal electrode disposed on a surface of the substrate ~~with the imaging element mounted thereon~~; an external electrode disposed on a rear surface of the substrate ~~imaging element mounted surface~~ ~~and at a position corresponding to the internal electrode~~; and an end face electrode disposed on ~~an end~~ a side face of the substrate, which connects the internal electrode and the external electrode, and

~~an end~~ the side face of the substrate, [[a]] an outer side face of the rib and ~~an end~~ a side face of the transparent plate, ~~which correspond to a side face of the package~~, form a substantially coplanar surface.
2. (CURRENTLY AMENDED) The solid-state imaging device according to claim 1, wherein the [[end]] side face of the substrate, the outer side face of the rib and the [[end]] side face of the transparent plate are in a plane formed by cutting them sequentially in a single operation.

3. (ORIGINAL) The solid-state imaging device according to claim 1, wherein an internal side face of the rib has a tilt such that the internal side face spreads outwardly from a face of the substrate toward the transparent plate.
4. (ORIGINAL) The solid-state imaging device according to claim 3, wherein the internal side face of the rib has a flat surface, and an angle of the tilt is within a range of  $2^{\circ}$  to  $12^{\circ}$  with respect to a direction perpendicular to the face of the substrate.
5. (ORIGINAL) The solid-state imaging device according to claim 1, wherein an orange peel skin pattern or a grained pattern is formed on an internal side face of the rib.
6. (ORIGINAL) The solid-state imaging device according to claim 1, wherein an internal side face of the rib has a flat surface, and an external side face and the internal side face of the rib are perpendicular to the face of the substrate.
7. (ORIGINAL) The solid-state imaging device according to claim 1,  
wherein the end face electrode is disposed in a recess that is formed on the end face of the substrate, and  
a surface of the end face electrode forms a substantially coplanar face with the end face of the substrate, or is recessed relative to the end face of the substrate.
8. (ORIGINAL) The solid-state imaging device according to claim 1, wherein a surface of the external electrode forms a substantially coplanar surface with the rear surface of the substrate.
9. (ORIGINAL) The solid-state imaging device according to claim 1, wherein a surface of the external electrode is recessed relative to the rear surface of the substrate.
10. (ORIGINAL) The solid-state imaging device according to claim 9,  
wherein an insulation film is formed on the rear face of the substrate, and

the insulation film and the external electrode are arranged so as not to overlap each other.

11. (ORIGINAL) The solid-state imaging device according to claim 9, wherein an insulation film is formed on the rear face of the substrate, and a peripheral portion of the external electrode and the insulation film are arranged so as to overlap each other.

12. (CURRENTLY AMENDED) A method for producing the solid-state imaging device ~~according to claim 1~~, comprising the steps of:

forming a top-side conductive layer and a bottom-side conductive layer on a top face and a bottom face of a base material ~~with a flat board form that is made of an insulation resin so that the top-side conductive layer and the bottom-side conductive layer correspond to a plurality of groups of the wirings for composing a plurality of the solid-state imaging devices~~, and forming a perforation conductive layer that penetrates through the base material so as to connect the top-side conductive layer and the bottom-side conductive layer;

providing a rib formation member for forming the rib on the base material at a boundary between regions, each of which is for fixing a forming one of the plurality of solid-state imaging element devices, so that the rib formation member extends is positioned transversely with respect to the top-side conductive layer above the perforation conductive layer;

fixing the imaging element in each region surrounded by the rib formation member and connecting the electrode of the imaging element and the top-side conductive layer by means of the thin metal wire;

fixing the transparent plate to a top end face of the rib formation member; and cutting the base material, the rib formation member and the transparent plate sequentially in a single operation in a direction perpendicular to the surface of the base material and in a direction that divides a width in a planar shape of the rib formation

member into halves so as to separate into respective pieces of the plurality of solid-state imaging devices ~~into the respective pieces.~~

13. (ORIGINAL) The method for producing the solid-state imaging device according to claim 12, wherein the rib formation member is formed in a lattice form.

14. (ORIGINAL) The method for producing the solid-state imaging device according to claim 12, wherein the rib formation member is formed on the base material by resin forming.

15. (ORIGINAL) The method for producing the solid-state imaging device according to claim 14, wherein the resin forming is carried out by molding using molds.

16. (ORIGINAL) The method for producing the solid-state imaging device according to claim 15, wherein, when forming the rib formation member by the resin molding, a sheet for suppressing generation of the resin flash is interposed between a mold for the resin molding and the base material.

17. (NEW) The solid-state imaging device according to claim 1, wherein the external electrode is disposed on a rear surface of the substrate at apposition corresponding to the internal electrode.